ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	PC. Bannockl	burn, Illinois, A	ll rights reserved utions.	under both	This docume level parts, t	ent is a declarati the declaration e	on of the su	ibstances s all lower	within the manufactur r level materials for w	rer listed it hich the m	tem. Note: nanufactur	if the item is an as rer has engineering	sembly with lowe responsibility.	
	21.1 IPC Web Site for Information on IPC-1752 Standard Form			Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia					als and M	als and Mfg Information			
Supplier Information														
Company name* Co			Company unique ID			Unique ID Authority					Response Date*			
nsemi									2024-05-20					
ontact Name Title - Contact			et	Phone - Contac			et* En			Email -	Email - Contact*			
Product-Env-Stewards Product Envir			viro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representativ			entative	ntative J		Phone - Representative*			Email - Representative*					
Product-Env-Stewards Pr			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Iten	n Number	Mfr Item Name		<u> </u>	Effective Date	Version	N	Manufacturing Site		Weight*	UOM	Unit Type	
	FODM3	DM3052R2-NF098 4SO RP TRIAC To		T&R	R			L	LITEONFG		74.91	mg	Each	
Manufacturing Proccess Informa	tion													
Terminal Plating / Grid Array M	aterial T	l Terminal Base Alloy		J-STD-020 MSL) MSL Rating F		Peak Process Body Temperature Max Time at		e Max Time at Peak	ak Temperature Numb		nber of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30 se		seconds 3			
Comments														
evel 1 - maximum time at peak temperat	ure during so	ldering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Coupling Gel	1.0	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.45	mg
			Supplier	Dimethyl Cyclosiloxanes	69430-24-6		0.1	mg
			Supplier	Trimethoxy(methyl)silane (C4H12O3Si)	1185-55-3		0.45	mg
Die	0.237	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.077	mg
			Supplier	Silicon (Si)	7440-21-3		0.16	mg
Die Attach	0.17	mg	Supplier	Silver (Ag)	7440-22-4		0.1326	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.0374	mg
Lead Frame	22.5	mg	Supplier	Silver (Ag)	7440-22-4		0.0022	mg
			Supplier	Zinc (Zn)	7440-66-6		0.027	mg
			Supplier	Iron (Fe)	7439-89-6		0.5175	mg
			Supplier	Copper (Cu)	7440-50-8		21.9465	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0067	mg
Mold Compound-Black	27.9	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		3.627	mg
			Supplier	Carbon Black (C)	1333-86-4		0.279	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		2.511	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		19.53	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.953	mg
Mold Compound-White	21.1	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		4.22	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		14.77	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.11	mg
Plating	1.95	mg	Supplier	Tin (Sn)	7440-31-5		1.95	mg
Wire Bond - Au	0.053	mg	Supplier	Gold (Au)	7440-57-5		0.053	mg